

BMD-30 / 33 / 35 / 36 EVK

Evaluation kit for BMD-30 / 33 / 35 / 36 modules

User guide



Abstract

This document describes how to set up the EVK-BMD-30 / 33 / 35 / 36 evaluation kits to evaluate BMD-30 / 33 / 35 / 36 modules. It also describes the different options for debugging and the development capabilities included in the evaluation board.

Document information

Title	BMD-30 / 33 / 35 / 36 EVK	
Subtitle	Evaluation kit for BMD-30 / 33 / 35 / 36 modules	
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Disclosure restriction		

This document applies to the following products:

Product name
BMD-300-Eval
BMD-301-Eval
BMD-330-Eval
BMD-350-Eval
BMD-360-Eval

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1 Product description

The BMD-3xx-EVAL kits from u-blox allow for stand-alone use of the BMD-300, BMD-301, and BMD-350 modules featuring the Nordic nRF52832 RF System on Chip (SoC), the BMD-330 module featuring the Nordic nRF52810 RF SoC, and the BMD-360 module featuring the Nordic nRF52811 RF SoC. Other u-blox modules have evaluation kits covered by other documents.

These evaluation kits provide a great starting point for almost any Bluetooth 5 Low Energy project. All features of the BMD-3xx are easily accessed from the evaluation board. A simple USB connection provides power, programming, and a virtual COM port. Four user buttons are available, as well as four LEDs and a reset button. All 32 GPIO are available on headers that are compatible with the Arduino form factor. This allows easy use of any existing Arduino shields. Current sense resistors allow for measuring current into the BMD-3xx module and into the shield.

This guide provides setup instructions for starting development and describes the hardware functionality of the BMD-3xx-evaluation boards.

1.1 Key features

- BMD-3xx series module
- On-board programming and debug (SEGGER J-Link-OB)
- Able to program external modules
- Virtual COM port over USB
- Full GPIO of the module
- Buttons and LEDs for user interaction
- NFC antenna connector
- 32.768 kHz Crystal
- CR2032 battery holder

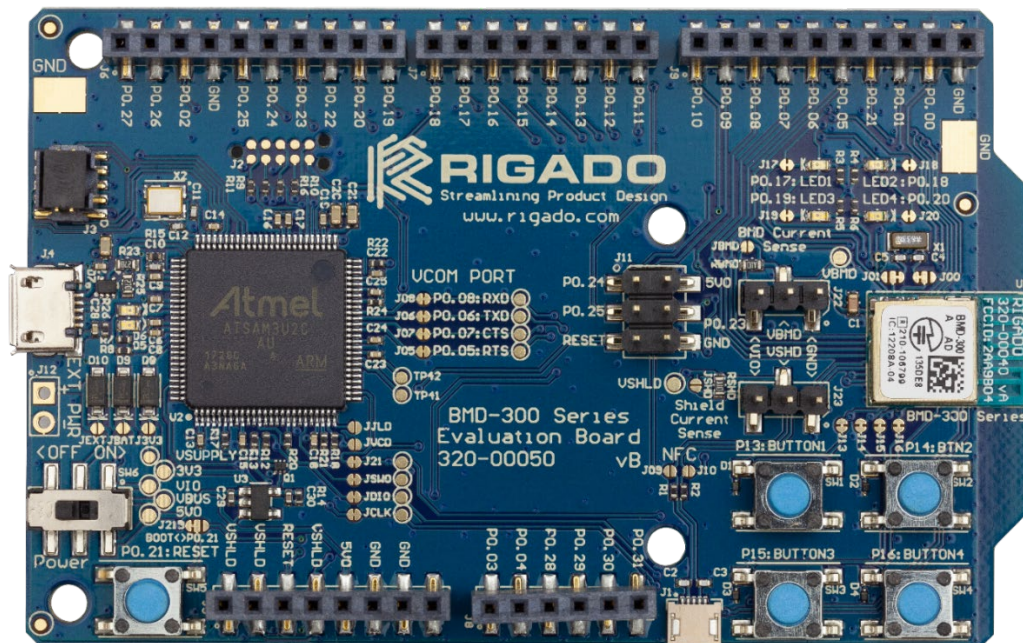


Figure 1: BMD-30 / 33 / 35 / 36 EVK evaluation board (Top view)

1.2 Kit includes

BMD-300 evaluation kit includes:

- BMD-300 evaluation board
- Micro-USB cable
- NFC antenna

BMD-301 evaluation kit includes:

- BMD-301 evaluation board
- Micro-USB cable
- NFC antenna
- 2.4 GHz antenna kit

BMD-330 or BMD-360 evaluation kit includes:

- BMD-330 or BMD-360 evaluation board
- Micro-USB cable

BMD-350 evaluation kit includes:

- BMD-350 evaluation board
- Micro-USB cable
- NFC antenna

1.3 Development tools

The tools listed below will aid in development with the BMD-3xx series Bluetooth modules. Not all tools will be required depending on which software suite is used.

Tool	Description
SEGGER Embedded Studio	SEGGER Embedded Studio is an easy-to-use integrated development environment with project management tools, editor and debugger supporting ARM Cortex devices. Full debug support including Real Time Terminal (RTT) output is also available. Available for Windows, macOS, and Linux. Free license for use with the Nordic nRF5 ICs and modules: http://license.segger.com/Nordic.cgi
SEGGER J-Link Software and Documentation Pack	J-Link Commander (JLink.exe) is a command line-based utility that can be used for verifying proper functionality of J-Link as well as for simple analysis of the target system. It supports some simple commands, such as memory dump, halt, step, go etc. to verify the target connection. Available for Windows, macOS, and Linux.
Nordic Semiconductor SDK	The nRF5 SDK is your first stop for building fully featured, reliable and secure applications with the nRF52 and nRF51 series. It offers developers a wealth of varied modules and examples right across the spectrum including numerous Bluetooth Low Energy profiles, Device Firmware Upgrade (DFU), GATT serializer and driver support for all peripherals on all nRF5 series devices. SDKs for Bluetooth Mesh, Thread, Zigbee and other protocols are also available.
Nordic Semiconductor nRF Connect for Desktop	nRF Connect is a cross-platform tool that enables testing and development with Bluetooth® Low Energy (previously called Bluetooth Smart). It allows easy setup of connections with other devices and uses these connections to read and write the external nodes. Available for Windows, macOS, and Linux.
Nordic Semiconductor nRF Connect for Mobile	nRF Connect for Mobile, previously known as nRF Master Control Panel, is a powerful generic tool that allows you to scan and explore your Bluetooth Low Energy devices and communicate with them. nRF Connect for Mobile supports several Bluetooth SIG adopted profiles, as well as the Device Firmware Update profile (DFU) from Nordic Semiconductor or Eddystone from Google. Available for iOS and Android.
Nordic Semiconductor Mobile Apps	Additional mobile utilities for your application development. Available for iOS and Android.

Table 1: Useful tools

2 Hardware description

Design files for each of the BMD-3xx evaluation boards may be requested from the [u-blox support team](#).

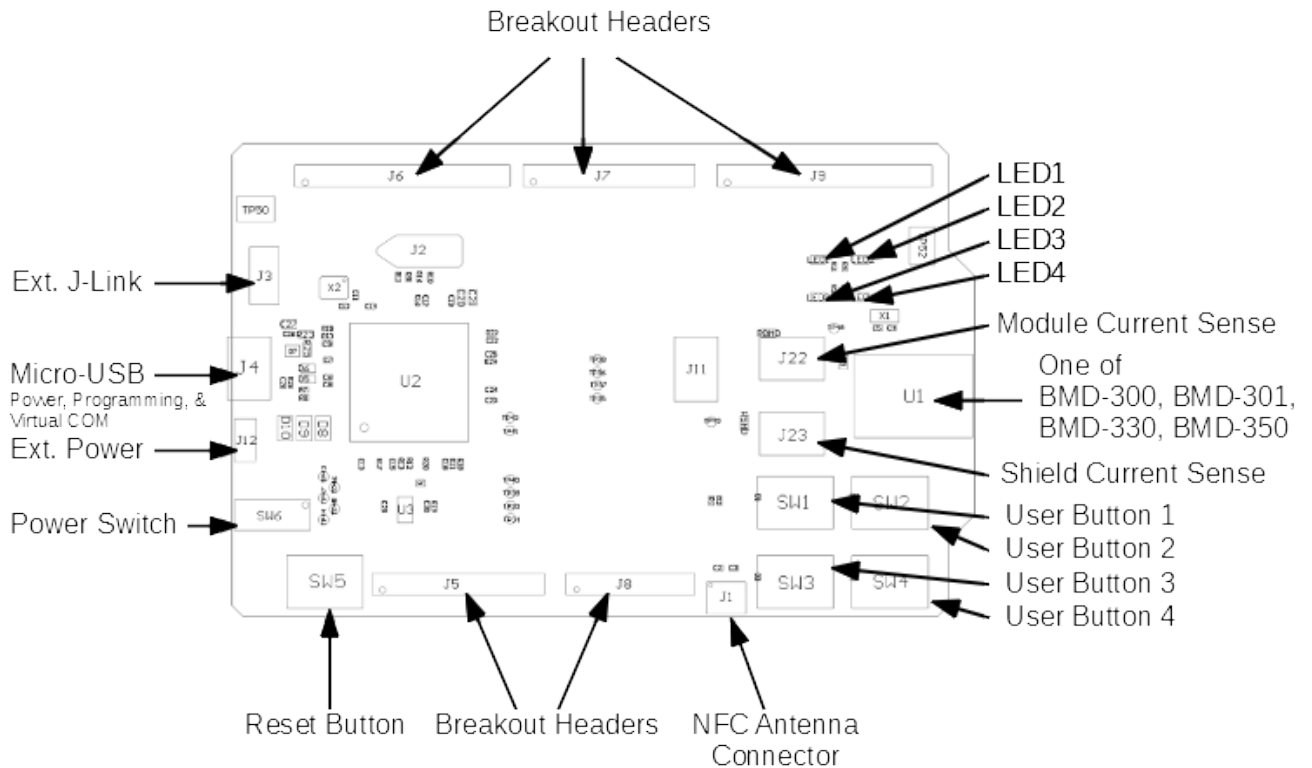


Figure 2: Assembly drawing (Top view)

2.1 Power

The BMD-3xx evaluation board has three possible power sources as listed below:

- USB
- CR2032 coin cell battery
- 2.54 mm through-hole connector

These power sources use protection diodes to prevent reverse voltage to any supply. This allows them to be used simultaneously. Solder jumpers are provided to allow by-passing any of the protection diodes eliminating the voltage drop across them.

Care should be taken to not damage the supplies when the protection is by-passed.

2.1.1 Powering the board

Typically, power will be provided by USB though VBUS, which will supply 5 V to the 3.3 V LDO regulator and to the shield connector. The 3.3 V LDO regulator will then power the VIO, VSHLD, and VBMD.

When powering the board from the CR2032 coin cell (3VDC) or the external power header, USB can be left disconnected. In this configuration, the interface IC is held in reset to conserve power.

Only if the power protection diodes are left intact can the USB be safely connected at the same time as the coin cell or external power is still applied, which allows for easy programming of the module.



The BMD-3xx modules have a configurable hardware reset. However, P0.21 is assumed to be used as the reset pin for all u-blox BMD and Nordic example projects, and thus the evaluation board hardware is configured to use P0.21 as a reset. The Reset button can be configured to connect to an input on the interface IC or to directly connect to P0.21.

When the reset button is directly connected to P0.21, it can be used as a fifth user button or as a reset button directly connected to the BMD module.

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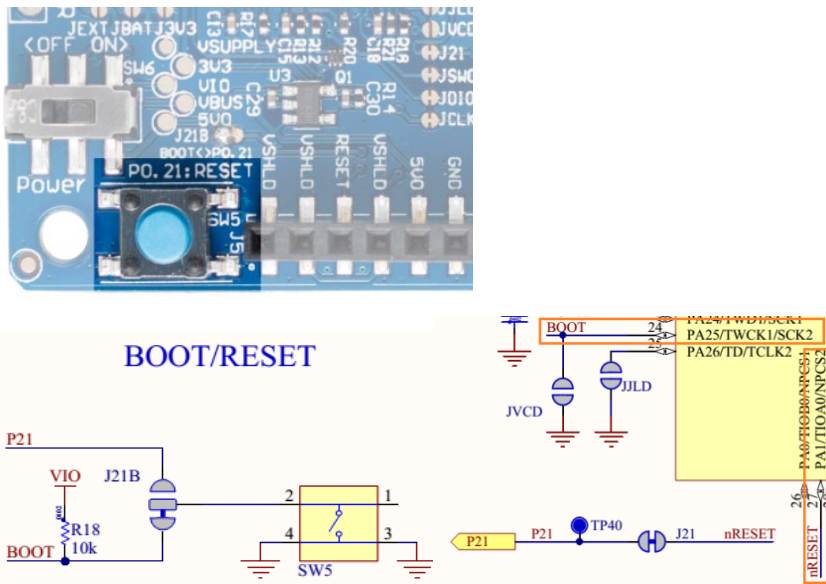


Figure 4: Schematic – Reset

2.3 Buttons

The evaluation board has four user buttons: Button 1, Button 2, Button 3, and Button 4. All buttons are active low; they will connect to ground when pressed. The button GPIO pins must be configured with internal pull-up resistors for proper operation when using the user buttons. The buttons and ESD protection can be completely removed from the circuit by breaking the associated jumper.

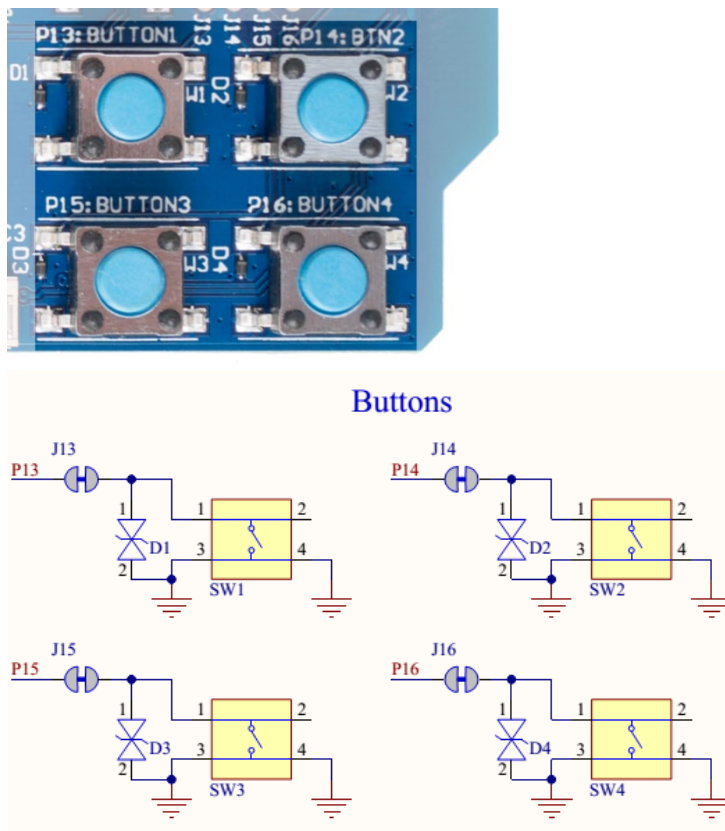


Figure 5: Schematic – User buttons

2.4 LEDs

Four User LEDs are provided on the evaluation board; two red and two green. LEDs are powered by VIO and are active low. The GPIO should be enabled for high drive when sinking current for the LEDs. The LEDs can be completely removed from the circuit by breaking the associated jumper.

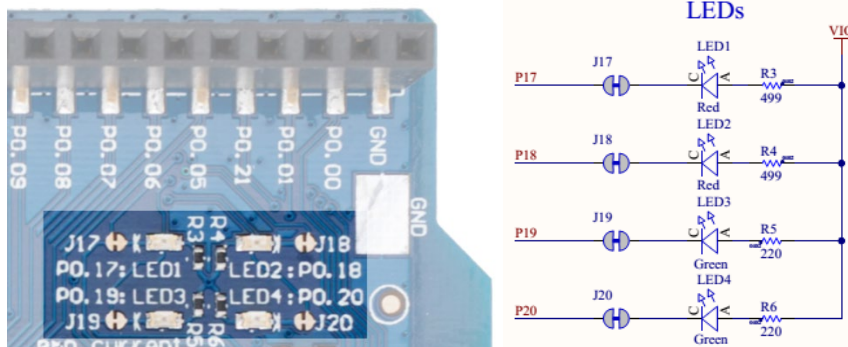


Figure 6: Schematic – User LEDs

2.5 Virtual COM port

The evaluation board allows for easy serial communication with the BMD-3xx series modules and a connected computer. The Interface IC provide a virtual COM USB device that connects to 4 GPIO pins on the module, allowing for UART communication with or without hardware flow control. The UART lines can be completely removed from the circuit by breaking the associated jumpers.

BMD-3xx Pin Name	BMD-3xx Function	Jumper	Interface IC Function
P0.05	RTS	J05	CTS
P0.06	TXD	J06	RXD
P0.07	CTS	J07	RTS
P0.08	RXD	J08	TXD

Table 2: Virtual COM Port

2.6 32 kHz crystal oscillator

The evaluation board has a 32.768 kHz crystal oscillator connected to the BMD-3xx module by default. This allows the module to use any of the three available low frequency (LF) clock sources: an internal calibrated RC oscillator, an internal synthesized clock (derived from the 32 MHz clock), or an external crystal oscillator. The external crystal oscillator is the most accurate and lowest power LF clock option. For applications without strict time keeping requirements, the internal calibrated RC oscillator is often suitable. The crystal is connected to the module through a solder select jumper, allowing either the crystal or the IO header to be connected to the module's GPIO pins.

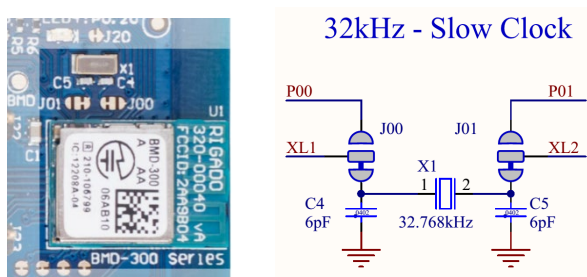


Figure 7: Schematic – 32 kHz crystal

2.7 NFC connector

Connection to an external NFC antenna is provided through a Molex flat-flex connector, part number 051281-0594. Capacitors “C2” and “C3” provide tuning of the NFC antenna for resonance at 15.56 MHz.

NFC is not supported on the BMD-330 or BMD-360. These components are not populated on the BMD_330-EVAL or BMD-360-EVAL.

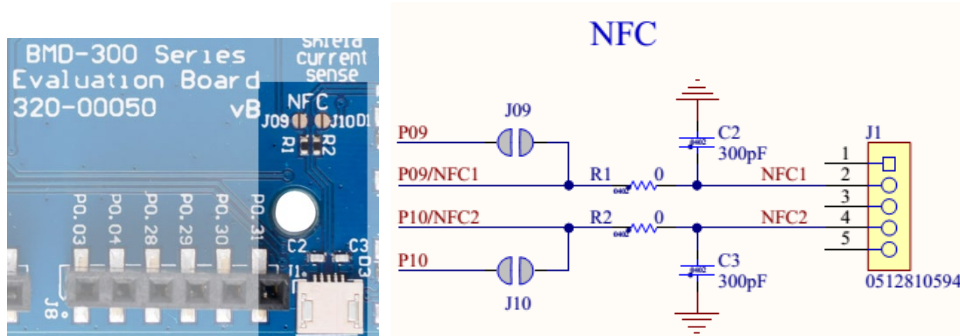


Figure 8: NFC connector

2.8 Current sensing headers

The evaluation board provides two current sensing headers. “JBMD” allows for power consumption measurement of the BMD-3xx series module and “JSHD” allows for power consumption measurement of shields connected to the Arduino-style headers (“VSHLD” power only).

Each 3-pin 2.54 mm header has two pins connected across a 1Ω current-sense resistor powering the module or the shield, and the third pin to ground. To measure current consumption, use a multimeter or other precision voltage measurement device to measure voltage drop across pins one and two. Current can also be measured directly by removing “RBMD” / “RSHD” and using a current meter in series with the two voltage pins. The default hardware configuration does not require any modification of the current sense headers for the BMD-3xx-EVAL to perform properly.

Only current flowing through “VBMD” into the module is measured; current sunk through GPIO pins is not measured.

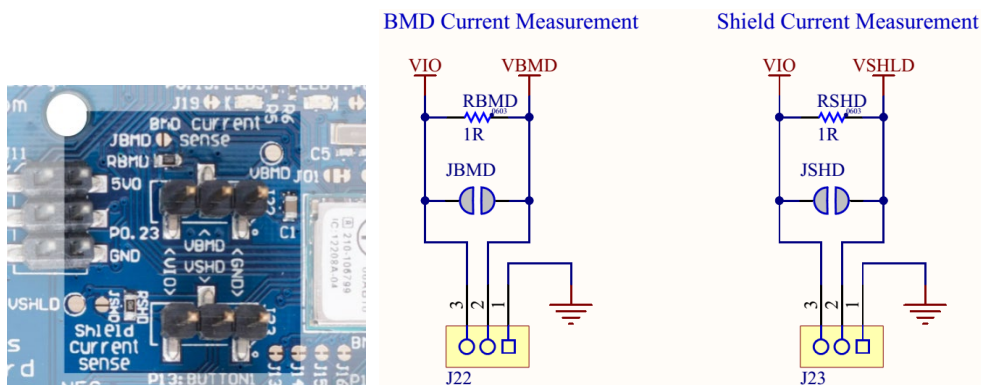


Figure 9: Current sensing header layout

2.9 External SEGGER J-Link™ Debug Interface

External target hardware can be connected to J3 for firmware programming and debug. The SEGGER debug interface is implemented as shown in Figure 10. J3 is implemented with a 2x5 10-pin header on 1.27 mm centers.

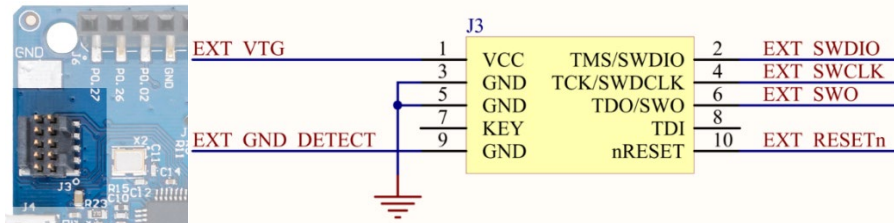


Figure 10: External J-Link debug interface

In order to enable the external J-Link connection, ensure the following are implemented on the target hardware:

- EXT_VTG is used by the debug interface as an input to sense power applied to the external circuit. Only voltages of 3.0 V to 3.3 V are supported. Other operating voltages require the use of an external J-Link Debug Probe. Connect EXT_VTG to the BMD-3xx series power supply (VCC) on the target hardware.
- EXT_GND_DETECT is used by the debug interface to detect the presence of external target hardware. Connect EXT_GND_DETECT to GND on the target hardware.
- Connect EXT_SWCLK and EXT_SWDIO to SWCLK and SWDIO on the target BMD-3xx, respectively.
- (Optional) Connect EXT_SWO and/or EXT_RESETn to P0.18 and P0.21 on the target BMD-3xx, respectively.
- Connect external power to the target hardware, then connect the BMD-3xx series evaluation Board to USB.



At this point, the debug interface will interact with the target hardware instead of the on-board BMD-3xx module.

2.10 GPIO jumpers

There are many solder bridge jumpers on the board available to allow for configurability of the GPIO. Most solder jumpers are used to remove on-board components from the module's GPIO nets, should they interfere with external circuitry added on the I/O headers. All GPIOs are directly connected to the I/O Headers by default, except P0.00 & P0.01 (32 kHz crystal) and P0.09 & P0.10 (NFC antenna). These are disconnected from the I/O headers as they would interfere with the default functions.

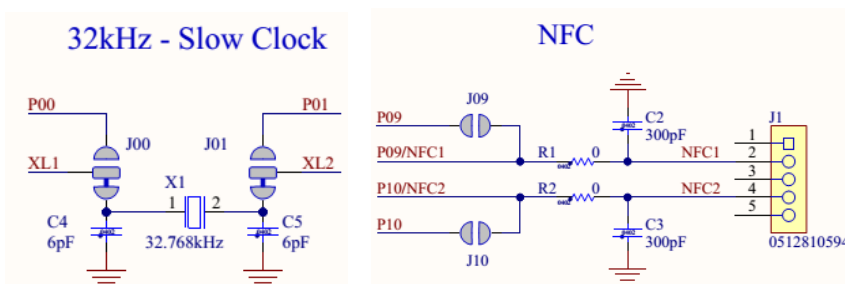


Figure 11: GPIOs disconnected from I/O headers

The GPIO jumpers are shown on the bottom side of the BMD-3xx series evaluation board:

BMD-300 Series			
GPIO	Function	Jumper	HW
P00	XL1	J00	
P01	XL2	J01	
P05	RTS	J05	
P06	TXD	J06	
P07	CTS	J07	
P08	RXD	J08	
P09	NFC1	J09 R1	
P10	NFC2	J10 R2	
P13	Button 1	J13	
P14	Button 2	J14	
P15	Button 3	J15	
P16	Button 4	J16	
P17	LED 1	J17	
P18	LED 2	J18	
P19	LED 3	J19	
P20	LED 4	J20	

Figure 12: GPIO Jumper summary

2.11 Header pin-out

Headers J5 - J9 and J11 break-out the IO signals from the BMD-3xx on 2.54 mm pitch headers.

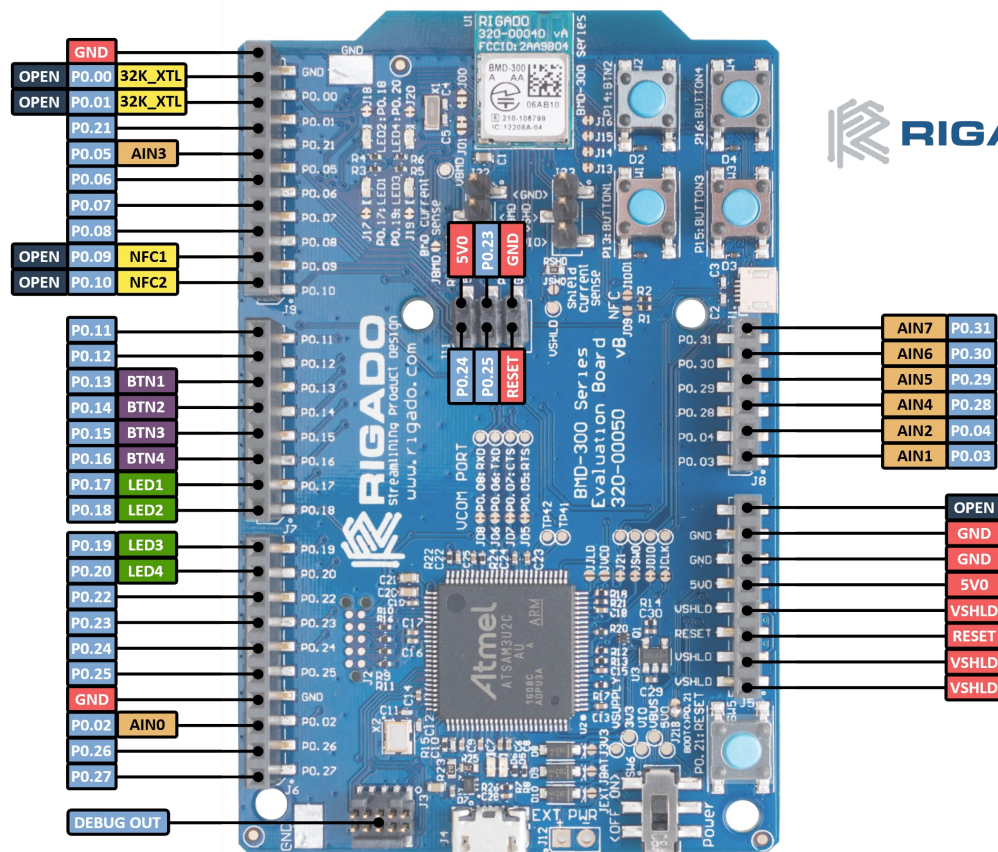


Figure 13: BMD-3xx series evaluation board pin-out

Header pin	Pin name	nRF52 port	Function
1	P0.24	P0.24	GPIO
2	5V0	-	+5.0 V USB Power
3	P0.25	P0.25	GPIO
4	P0.23	P0.23	GPIO
5	RESET	P0.21	RESET_N
6	GND		Ground

Table 3: Header J11

Header pin	Pin name	nRF52 port	Function
10	GND		Ground
9	P0.00	P0.00	OPEN / GPIO
8	P0.01	P0.01	OPEN / GPIO
7	P0.21	P0.21	RESET_N / GPIO
6	P0.05	P0.05	GPIO / AIN3
5	P0.06	P0.06	GPIO
4	P0.07	P0.07	GPIO
3	P0.08	P0.08	GPIO
2	P0.09	P0.09	OPEN / GPIO
1	P0.10	P0.10	OPEN / GPIO

Table 4: Header J9

Header pin	Pin name	nRF52 port	Function
6	P0.31	P0.31	GPIO / AIN7
5	P0.30	P0.30	GPIO / AIN6
4	P0.29	P0.29	GPIO / AIN5
3	P0.28	P0.28	GPIO / AIN4
2	P0.04	P0.04	GPIO / AIN2
1	P0.03	P0.03	GPIO / AIN1

Table 5: Header J8

Header pin	Pin name	nRF52 port	Function
8	P0.11	P0.11	GPIO
7	P0.12	P0.12	GPIO
6	P0.13	P0.13	GPIO
5	P0.14	P0.14	GPIO / TRACED[3]
4	P0.15	P0.15	GPIO / TRACED[2]
3	P0.16	P0.16	GPIO / TRACED[1]
2	P0.17	P0.17	GPIO
1	P0.18	P0.18	GPIO / TRACED[0]

Table 6: Header J7

Header pin	Pin name	nRF52 port	Function
10	P0.19	P0.19	GPIO
9	P0.20	P0.20	GPIO / TRACECLK
8	P0.22	P0.22	GPIO
7	P0.23	P0.23	GPIO
6	P0.24	P0.24	GPIO
5	P0.25	P0.25	GPIO
4	GND	GND	Ground
3	P0.02	P0.02	GPIO / AINO
2	P0.26	P0.26	GPIO
1	P0.27	P0.27	GPIO

Table 7: Header J6

Header pin	Pin name	nRF52 port	Function
8	-	-	
7	GND	-	Ground
6	GND	-	Ground
5	5V0	-	+5.0 V USB Power
4	VSHLD	-	+3.3 V Shield Power
3	RESET	P0.21	RESET_N
2	VSHLD	-	+3.3 V Shield Power
1	VSHLD	-	+3.3 V Shield Power

Table 8: Header J5

3 Setting up the evaluation board

This section provides information on how to set up and program the BMD-3xx series evaluation kit with an example application.

3.1 Set up the tool chain

1. Install [SEGGER Embedded Studio](#) and [request a license](#).
2. Download the latest [nRF5 SDK](#). Unzip it to a convenient working directory.

Do not alter the directory trees. The examples are configured for relative path positions. Do not use spaces in the directory path.

3. Install [nRF Connect on desktop PC](#) and optionally one of the [mobile versions](#). nRF Connect can be used directly with the Device Under Test (DUT) evaluation board for programming and other features.

If using nRF Connect on a desktop, a second evaluation board or a [nRF52 USB Dongle](#) will be needed to make BLE connections with your DUT.

4. Install the [SEGGER J-Link Commander](#). If presented with a screen to select different IDEs, ensure at least the “SEGGER Embedded Studio ARM” line is selected:

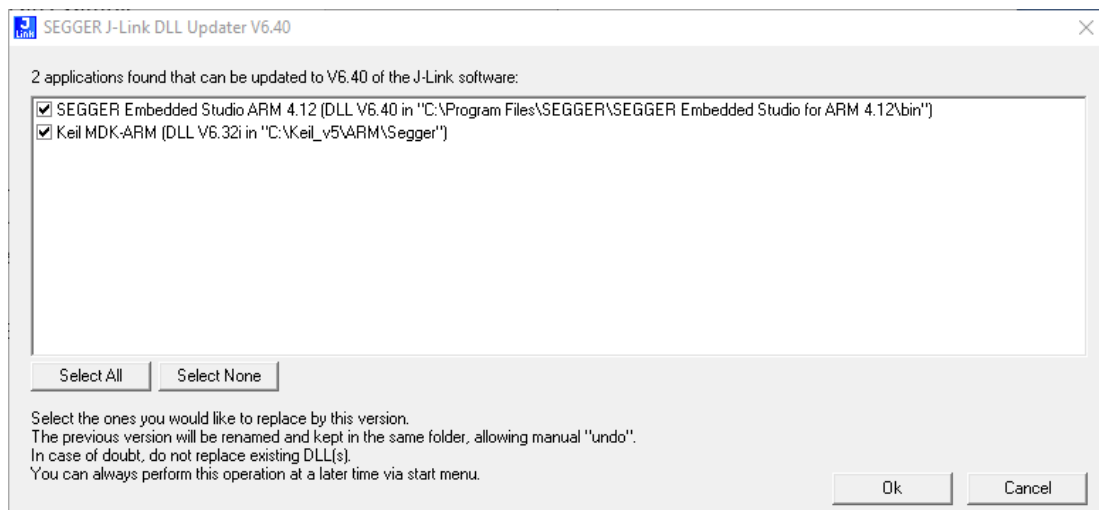


Figure 14: SEGGER J-Link Commander Install

5. You may need to add the install location to the system PATH. The default location for the J-Link commander is, “C:\Program Files (x86)\SEGGER\JLink_Vnnn”, where “nnn” is the version number.
6. Install [nRF Toolbox](#) for your mobile device. This will be used with the example below.


3.2 Connect BMD-3xx evaluation kit to a computer

The evaluation board is provided with an on-board SEGGER J-Link programmer/debugger.


7. If using the BMD-301-EVAL, connect one of the 2.4GHz antennas from the kit to the module.

Note that the U.FL connector is intended for limited connect / disconnect cycles.

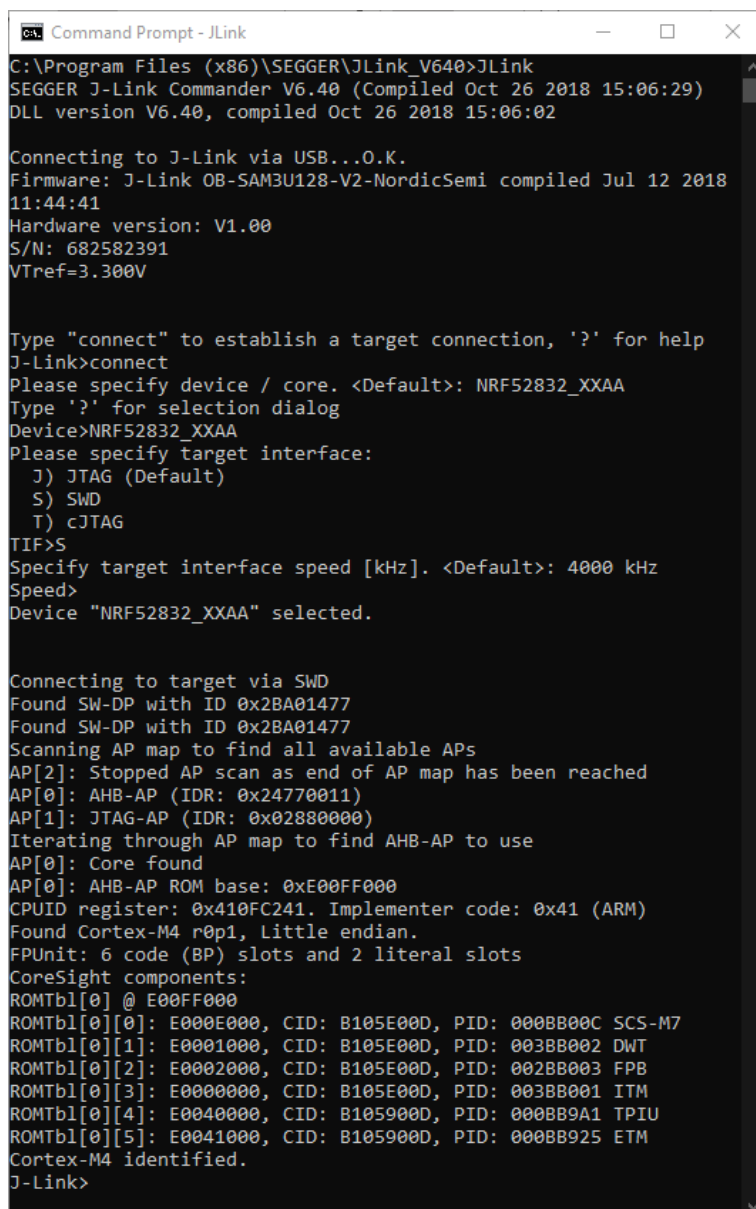
1. Connect the board to a computer using the USB cable provided.

 The status LED, D5, will flash and then turn solid once the USB device is enumerated. Some flickering is normal.

2. After a few seconds the computer will recognize the evaluation board as a J-Link device and install the USB-Virtual COM Port device driver.
3. Run the J-Link Commander:
 - 3.1. JLink on Windows
 - 3.2. JLinkExe on macOS and Linux

 If prompted to update the J-Link firmware, accept and perform the update.

4. Type “connect” at the J-Link> prompt
5. Enter the device type at the Device> prompt
 - 5.1. Type nRF52832_XXAA for the BMD-300, BMD-301, or BMD-350
 - 5.2. Type nRF52810_XXAA for the BMD-330
 - 5.3. Type nRF52811_XXAA for the BMD-360
6. Enter s to select the SWD interface and accept the default for the speed.
7. J-Link will respond with several items. Here is a sample output:



```

C:\Program Files (x86)\SEGGER\JLink_V640>JLink
SEGGER J-Link Commander V6.40 (Compiled Oct 26 2018 15:06:29)
DLL version V6.40, compiled Oct 26 2018 15:06:02

Connecting to J-Link via USB...O.K.
Firmware: J-Link OB-SAM3U128-V2-NordicSemi compiled Jul 12 2018
11:44:41
Hardware version: V1.00
S/N: 682582391
VTref=3.300V

Type "connect" to establish a target connection, '?' for help
J-Link>connect
Please specify device / core. <Default>: NRF52832_XXAA
Type '?' for selection dialog
Device>NRF52832_XXAA
Please specify target interface:
  J) JTAG (Default)
  S) SWD
  T) cJTAG
TIF>S
Specify target interface speed [kHz]. <Default>: 4000 kHz
Speed>
Device "NRF52832_XXAA" selected.

Connecting to target via SWD
Found SW-DP with ID 0x2BA01477
Found SW-DP with ID 0x2BA01477
Scanning AP map to find all available APs
AP[2]: Stopped AP scan as end of AP map has been reached
AP[0]: AHB-AP (IDR: 0x24770011)
AP[1]: JTAG-AP (IDR: 0x02880000)
Iterating through AP map to find AHB-AP to use
AP[0]: Core found
AP[0]: AHB-AP ROM base: 0xE00FF000
CPUID register: 0x410FC241. Implementer code: 0x41 (ARM)
Found Cortex-M4 r0p1, Little endian.
FPUnit: 6 code (BP) slots and 2 literal slots
CoreSight components:
ROMTbl[0] @ E00FF000
ROMTbl[0][0]: E000E000, CID: B105E00D, PID: 000BB00C SCS-M7
ROMTbl[0][1]: E0001000, CID: B105E00D, PID: 003BB002 DWT
ROMTbl[0][2]: E0002000, CID: B105E00D, PID: 002BB003 FPB
ROMTbl[0][3]: E0000000, CID: B105E00D, PID: 003BB001 ITM
ROMTbl[0][4]: E0040000, CID: B105900D, PID: 000BB9A1 TPIU
ROMTbl[0][5]: E0041000, CID: B105900D, PID: 000BB925 ETM
Cortex-M4 identified.
J-Link>
  
```


Figure 15: J-Link Commander Output


8. This confirms that the evaluation board is properly recognized.
9. While still in the J-Link Commander session, save the pre-programmed public Bluetooth address by typing: `savebin mac_addr.bin 0x10001080 8`
10. Save the file `mac_addr.bin` to a convenient location for future use.
11. Exit the J-Link session by typing: `exit`

At this point, a file titled `mac_addr.bin` will be saved in the current directory. The contents will contain the Bluetooth device (MAC) address in little-endian format:

```
33 22 11 C3 09 60 FF FF
```

This corresponds to the address `60:09:C3:11:22:33`. The last two `FF` values are fillers to complete the 8-byte read.

 This binary file may be used to restore the Bluetooth device address after performing an erase or recover with the J-Link command: `loadbin mac_address.bin 0x10001080`

 The Bluetooth device address is also printed on the module label. See the module data sheet for details.


3.3 Prepare the module for programming

The BMD-300, BMD-301 and BMD-350 modules are shipped from the factory with factory firmware to support legacy designs. This firmware must be erased prior to programming new code. Run the following at a command prompt:

```
nrfjprog -f nrf52 -recover
```

The BMD-330 and BMD-360 modules do not have factory firmware and do not require erasure.


3.4 Open an example project

 When selecting examples from the SDK, note the following cross references:

u-blox evaluation board	Nordic SoC	Preferred Nordic SoftDevice	Compatible Nordic DK
BMD-300-EVAL	nRF52832	S132	PCA10040 / nRF52 DK
BMD-301-EVAL	nRF52832	S132	PCA10040 / nRF52 DK
BMD-350-EVAL	nRF52832	S132	PCA10040 / nRF52 DK
BMD-330-EVAL	nRF52810	S112	PCA10040e / nRF52 DK (If PCA10040e is not available, select PCA10040)
BMD-360-EVAL	nRF52811	S113	PCA10056e / nRF52840 DK (If PCA10056e is not available, select PCA10056) Refer to Appendix A for example settings.

Table 9: BMD evaluation boards with Nordic DK cross reference

For this guide, the nRF SDK v16.0.0 Heart Rate Service example for the BMD-300-EVAL will be used.

 Whenever possible, use the latest SDK version. The “nRF5_SDK_xx.x.x_yyyyyyy” directory may change. The folders under usually remain the same from version to version.

1. Navigate to the location of the heart rate example from the SDK, typically `<unzipped_location>\nRF5_SDK_16.0.0_98a08e2\examples\ble_peripheral\ble_app_hrs`
2. Select the DK Board, SoftDevice and IDE directories. Here is the full path: `<unzipped_location>\nRF5_SDK_16.0.0_98a08e2\examples\ble_peripheral\ble_app_hrs\pca10040\s132\ses`

3. Open the project file (`ble_app_hrs_pca10040_s132.emProject`) to start the SEGGER Embedded Studio IDE
4. Build the project (<F7>)
5. Once the build is successful, you can download the application code onto the module Board (`Target | Download ble_app_hrs_pca10040_s132`)



The first time the board is programmed, both the SoftDevice and the application will be downloaded to the module. Once the SoftDevice is loaded, subsequent downloads will only transfer the application. If you need to change SoftDevice versions, erase the board through the IDE: (`Target | Erase All`)

1. On a mobile device, open the nRF Toolbox application. Select the Heart Rate Monitor.
2. Tap Connect. You should see the evaluation board advertising as “Nordic_HRM”.
3. Select this device to see the simulated heart rate being transmitted from the BMD-3xx.

Additional training videos for SEGGER Embedded Studio can be viewed [here](#).

A Appendix

A.1 SDK example configuration for BMD-360-Eval

The BMD-360-Eval follows the PCA10040 board pin-out from Nordic Semiconductor. Two small changes are required in the project options in order to assign the correct GPIO and reset pins. In order to make these changes, follow the directions below.

- 1) Find the project options by right-clicking on the project name.

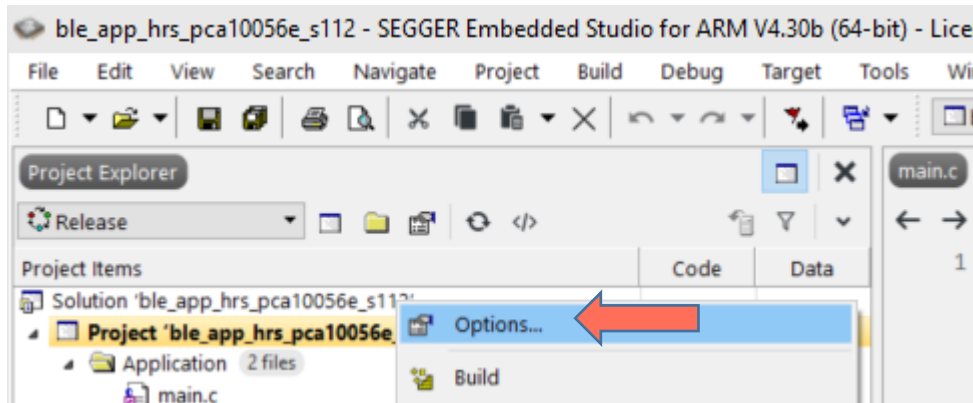


Figure 16: Project options

- 2) Select the "Common" configuration.

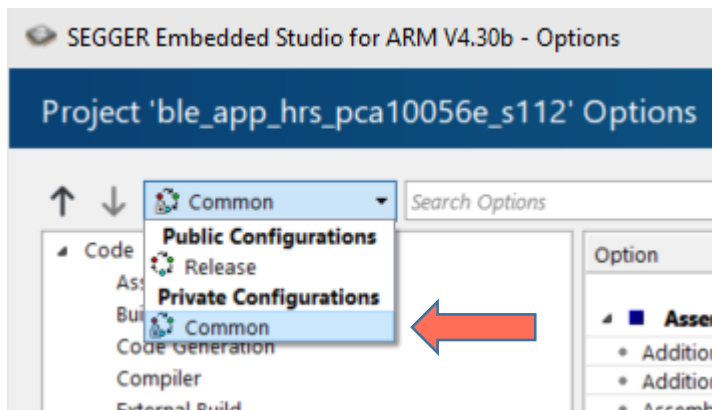


Figure 17: Common configuration

- 3) Select the “Preprocessor” item under the “Code list”.

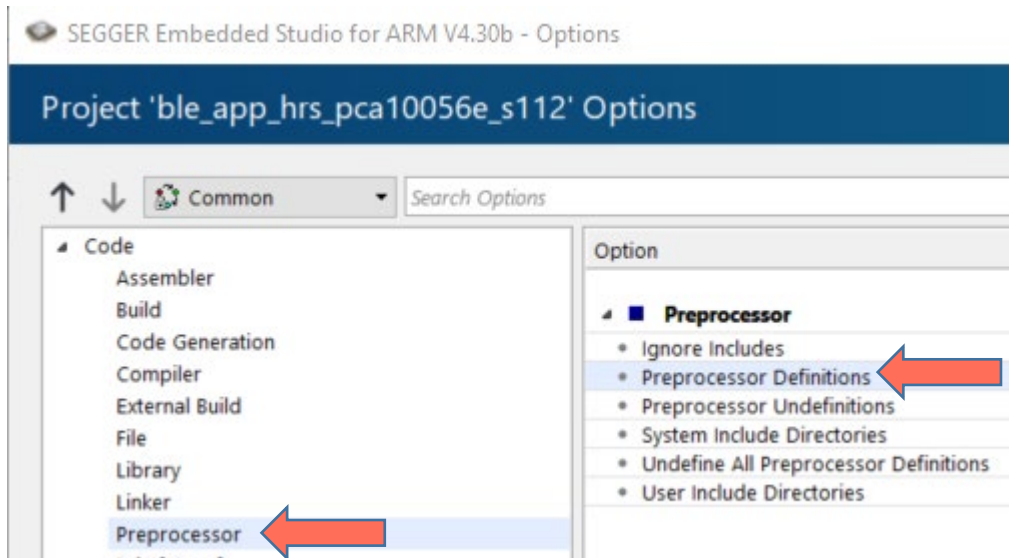


Figure 18: Preprocessor options

- 4) Double-click on “Preprocessor Definitions” to display the options in an editable dialog box.

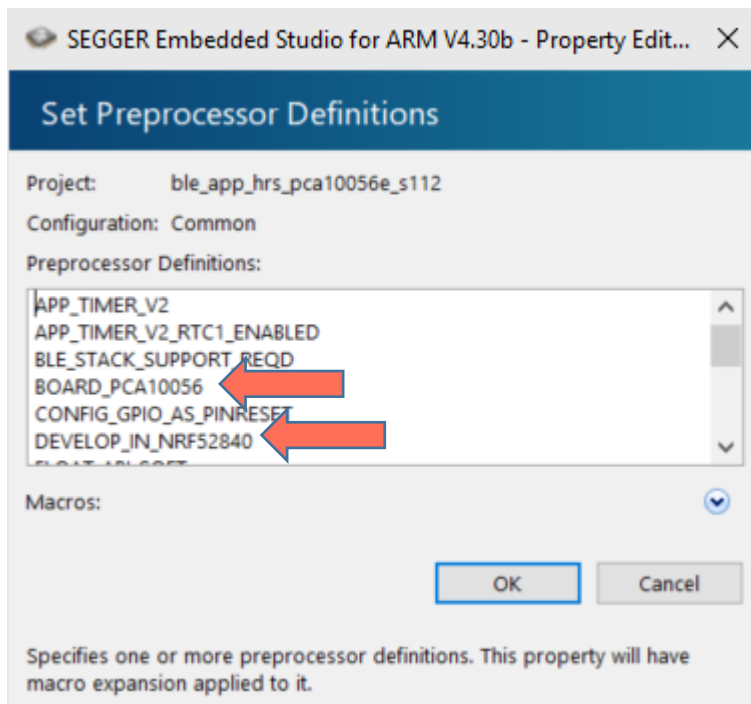


Figure 19: Preprocessor definitions to modify

- 5) Modify the directive “BOARD_PCA10056” to “BOARD_PCA10040”.
- 6) Remove the directive “DEVELOP_IN_NRF52840”.

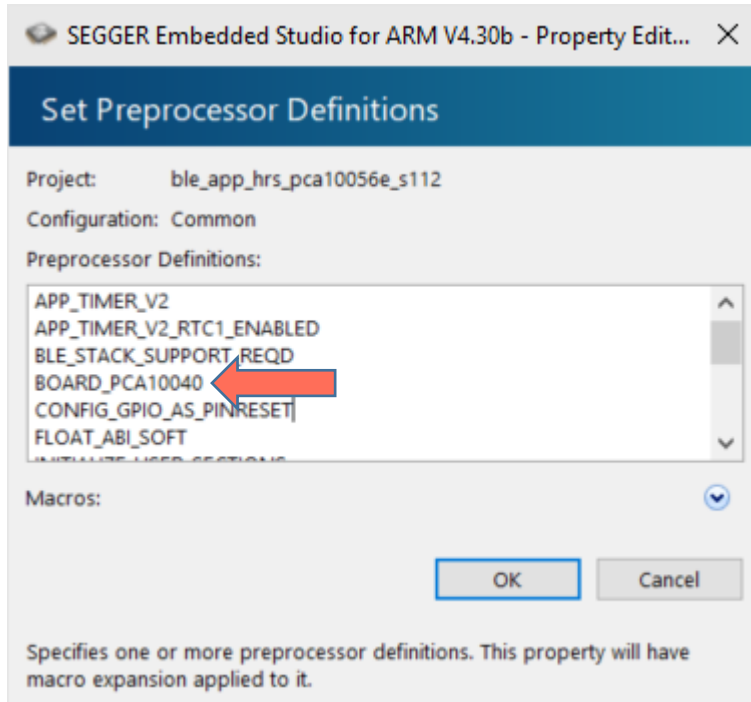



Figure 20: Resulting preprocessor definitions

7) Click OK to close each dialog box and save the settings.

Related documents

- [1] BMD-300 data sheet, doc. no. [UBX-19033350](#)
- [2] BMD-301 data sheet, doc. no. [UBX-19033351](#)
- [3] BMD-350 data sheet, doc. no. [UBX-19033354](#)
- [4] BMD-330 data sheet, doc. no. [UBX-19033352](#)
- [5] BMD-360 data sheet, doc. no. [UBX-19039466](#)
- [6] Using public IEEE address from UICR application note, doc. no. [UBX-19055303](#)
- [7] Add Nordic Semiconductor DFU to SDK example app note, doc. no. [UBX-19050198](#)
- [8] [Nordic nRF52810 product specification](#)
- [9] [Nordic nRF52811 product specification](#)
- [10] [Nordic nRF52832 product specification](#)
- [11] [S112 SoftDevice specification](#)
- [12] [S113 SoftDevice Specification](#)
- [13] [S132 SoftDevice specification](#)
- [14] u-blox package information guide, doc. no. [UBX-14001652](#)

 For regular updates to u-blox documentation and to receive product change notifications, register on our homepage (www.u-blox.com).

Revision history

Revision	Date	Name	Comments
1.0	04-May-2016		Initial release.
1.0.1	06-May-2016		Added link to reference design files in Section 4, updated logo
1.1	28-Jul-2016		Updated images, Added section on External J-Link connector, corrected section numbering
1.2	09-Sep-2016		Added BMD-350 evaluation kit information, document links
1.3	09-May-2017		Corrected BMD-350 hardware kit list
2.0	14-Dec-2018		Updated to new document format Changed tools to recent Nordic Semiconductor versions
2.1	05-Jun-2019		Added BMD-360-EVAL kit information, document links Updated Nordic Semiconductor links
R08	24-Oct-2019	brec, smos	Document converted from Rigado BMD-3xx user guide to u-blox BMD-3xx EVK user guide
R09	05-Dec-2019	brec	Updated filename and title to BMD-30 / 33 / 35 / 36 EVK
R10	17-Jan-2020	brec	Added Appendix A to show BMD-360 example settings, updated table 9 to include reference to Appendix A, added new app note references in related documents list, updated Bluetooth device address details in section 3.2, added note regarding BMD-300, BMD-301, and BMD-350 factory firmware, removed type number from product list as it applies to all type numbers

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